TLV5619 2.7 V TO 5.5 V 12-BIT PARALLEL DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS172B - DECEMBER 1997 - REVISED JUNE 1998

- Single Supply 2.7-V to 5.5-V Operation
- • ±0.4 LSB Differential Nonlinearity (DNL), ±1.5 LSB Integral Nonlinearity (INL)
- 12-Bit Parallel Interface
- Compatible With TMS320 DSP
- Internal Power On Reset
- Settling Time 1 μs Typ
- Low Power Consumption:
 8 mW for 5-V Supply
 4.3 mW for 3-V Supply
- Reference Input Buffers
- Voltage Output
- Monotonic Over Temperature

description

The TLV5619 is a 12-bit voltage output DAC with a microprocessor and TMS320 compatible parallel interface. The 12 data bits are double buffered so that the output can be updated asynchronously using the $\overline{\text{LDAC}}$ pin. During normal operation, the device dissipates 8 mW at a 5-V supply and 4.3 mW at a 3-V supply. The power consumption can be lowered to 50 nW by setting the DAC to power down mode.

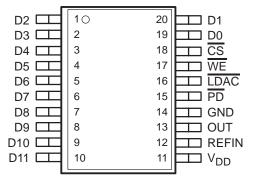
The output voltage is buffered by a ×2 gain rail-to-rail amplifier, which features a Class A output stage to improve stability and reduce settling time.

Asynchronous Update

applications

- Battery Powered Test Instruments
- Digital Offset and Gain Adjustment
- Battery Operated/Remote Industrial Controls
- Machine and Motion Control Devices
- Cordless and Wireless Telephones
- Speech Synthesis
- Communication Modulators
- Arbitrary Waveform Generation

DW OR PW PACKAGE (TOP VIEW)



AVAILABLE OPTIONS

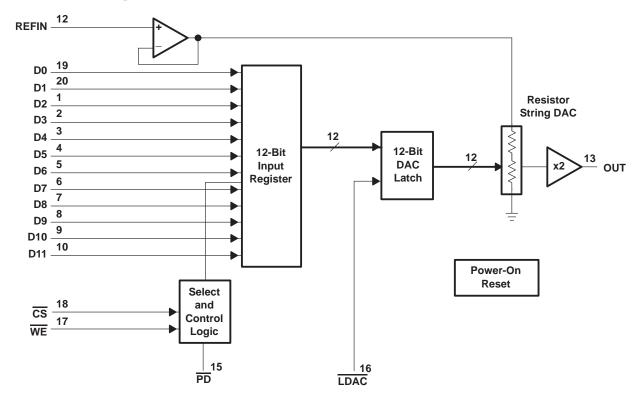
PACKAGE							
TA	SMALL OUTLINE TSSOP (DW) (PW)						
0°C to 70°C	TLV5619CDW	TLV5619CPW					
-40°C to 85°C	TLV5619IDW	TLV5619IPW					



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



functional block diagram



Terminal Functions

TERMINAL		1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
CS	18	I	Chip select
D0 (LSB)-D11 (MSB)	19, 20, 1 – 10	I	Parallel data input
GND	14		Ground
LDAC	16	I	Load DAC
OUT	13	0	Analog output
PD	15	I	When low, disables all buffer amplifier voltages to reduce supply current
REFIN	12	I	Voltage reference input
V_{DD}	11		Positive power supply
WE	17	-1	Write enable

TLV5619 2.7 V TO 5.5 V 12-BIT PARALLEL DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V _{DD} (5-V Supply)			4.5	5	5.5	V
Supply voltage, V _{DD} (3-V Supply)			2.7	3	3.3	V
High-level digital input voltage, VIH	V_{DD}		2			V
Low-level digital input voltage, V _{IL}	V_{DD}				0.8	V
Reference voltage, V _{ref} to REFIN terminal (5-V Supply)		0	2.048	V _{DD} -1.5	V
Reference voltage, V _{ref} to REFIN terminal (V _{DD} -1.5	V		
Load resistance, R _L			2	10		kΩ
Load capacitance, CL			0 2.048 V _{DD} -1.5 V 0 1.024 V _{DD} -1.5 V 2 10 k 100 p 0 70 °		pF	
Load capacitance, C _L Operating free-air temperature, T _A	TLV5619C		0		70	°C
	TLV5619I		-40		85	°C

NOTES: 1. The recommended operating levels for both V_{IH} and V_{IL} apply to all valid values of V_{DD} .

2. Reference input voltages greater than $V_{\mbox{DD}}/2$ will cause output saturation for large DAC codes.



2.7 V TO 5.5 V 12-BIT PARALLEL DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS172B - DECEMBER 1997 - REVISED JUNE 1998

electrical characteristics over recommended operating free-air temperature range, supply voltages, and reference voltages (unless otherwise noted)

static DAC specifications

	PARAMETER		TEST CONDITION	S	MIN	TYP	MAX	UNIT
	Resolution		Vref(REFIN) = 2.048 V at 5 V, 1.024 V at 3 V		12			bits
	Integral nonlinearity (INL)		Vref(REFIN) = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 3		±1.5	±4	LSB
	Differential nonlinearity (DNL)		Vref(REFIN) = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 4		± 0.4	± 1	LSB
EZS	Zero-scale error (offset error at	zero scale)	V _{ref(REFIN)} = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 5		±3	±20	mV
	Zero-scale-error temperature coefficient		Vref(REFIN) = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 6		3		ppm/°C
EG	Gain error		Vref(REFIN) = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 7		±0.25	±0.5	% of FS voltage
	Gain error temperature coefficient		V _{ref} (REFIN) = 2.048 V at 5 V, 1.024 V at 3 V,	See Note 8		1		ppm/°C
PSRR	Dower aupply rejection ratio	Zero scale	See Notes 9 and 10			65		dB
FORK	Power-supply rejection ratio	Gain	See Notes a and 10			65		uБ

- NOTES: 3. The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.
 - 4. The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
 - 5. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
 - 6. Zero-scale-error temperature coefficient is given by: EZS TC = [EZS (T_{max}) EZS (T_{min})]/V_{ref} × 10⁶/(T_{max} T_{min}).
 - 7. Gain error is the deviation from the ideal output $(2 \times V_{ref} 1 \text{ LSB})$ with an output load of $10 \text{ k}\Omega$ excluding the effects of the zero-error.
 - 8. Gain temperature coefficient is given by: $E_G TC = [E_G(T_{max}) E_G(T_{min})]/V_{ref} \times 10^6/(T_{max} T_{min})$.
 - 9. Zero-scale-error rejection ratio (EZS-RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
 - 10. Gain-error rejection ratio (EG-RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage after subtracting the zero scale change.

output specifications

	PARAMETER	TEST CONDITION	S	MIN	TYP	MAX	UNIT
VO	Voltage output range	$R_L = 10 \text{ k}\Omega$		0		V _{DD} -0.4	V
	Output load regulation accuracy	VO(OUT) = 4.096 V, 2.048 V,	R _L = 2 kΩ		0.1	0.29	% of FS voltage
loos, ,	Output short circuit source current	$V_{O(OUT)} = 0 V,$	5-V Supply		100		mA
IOSC(source)		Full scale code	3-V Supply		25		IIIA
IO(source)	Output source current	R _I = 100 Ω	5-V Supply		10		mA
	Output source current	N_ = 100 32	3-V Supply		10		ША



TLV5619 2.7 V TO 5.5 V 12-BIT PARALLEL DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

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electrical characteristics over recommended operating free-air temperature range, supply voltages, and reference voltages (unless otherwise noted)

reference input (REFIN)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{ref}	Reference input voltage	See Note 11	0		V _{DD} -1.5	V
Ri	Reference input resistance			10		МΩ
Ci	Reference input capacitance			5		pF
	Reference feed through	REFIN = 1 V _{pp} at 1 kHz + 1.024 V dc (see Note 12)		-60		dB
	Reference input bandwidth	REFIN = 0.2 V _{pp} + 1.024 V dc at –3 dB		1.4		MHz

NOTES: 11. Reference input voltages greater than V_{DD}/2 will cause output saturation for large DAC codes.

digital inputs (D0 - D11, CS, WE, LDAC, PD)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
lн	High-level digital input current	$V_I = V_{DD}$			1	μΑ
I _I L	Low-level digital input current	V _I = 0 V			-1	μΑ
Ci	Input capacitance			8		pF

power supply

	PARAMETER TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I _{DD} Power supply current	Power cupply current	No load, All inputs 0 V or V _{DD}	5-V Supply		1.6	3	mΛ
	Power supply current		3-V Supply		1.44	2.7	mA
	Power down supply current				0.01	10	μΑ

^{12.} Reference feedthrough is measured at the DAC output with an input code = 0x000 and a V_{ref(REFIN)} input = 1.024 V dc + 1 V_{pp} at 1 kHz.

operating characteristics over recommended operating free-air temperature range, supply voltages, and reference voltages (unless otherwise noted)

analog output dynamic performance

	PARAMETER	TES	T CONDITIONS		MIN	TYP	MAX	UNIT
SR	Slew rate	$C_L = 100 \text{ pF},$ $R_I = 10 \text{ k}\Omega,$	V _{ref} (REFIN) = 2.048 V, 1.024 V,	5-V Supply	8	12		V/μs
SK .	Siew fate	Code 32 to code 4095, Code 4095 to code 32,	V _O from 10% to 90% 90% to 10%	3-V Supply	6	9		V/μs
t _S	Output settling time (full scale)	To ± 0.5 LSB, R _L = 10 kΩ,	C _L = 100 pF, See Note 13			1	3	μs
	Glitch energy	DIN = all 0s to all 1s				5		nV-s
S/N	Signal to noise	f _S = 480 kSPS, BW = 20 kHz, C _L = 100 pF,	f_{OUT} = 1 kHz, R _L = 10 kΩ T _A = 25°C, See Note 14	5-V Supply	65	78		
S/(N+D)	Signal to noise + distortion	f _S = 480 kSPS, BW = 20 kHz,	f _{OUT} = 1 kHz,	5-V Supply	58	67		
3/(14+15)	Signal to hoise + distortion	$C_L = 100 \text{ pF},$	$T_A = 25^{\circ}C$, See Note 14	3-V Supply	58	69		dB
	Total harmonic distortion	$f_S = 480 \text{ kSPS},$ BW = 20 kHz, C _L = 100 pF,	f_{OUT} = 1 kHz, R _L = 10 k Ω , T _A = 25°C, See Note 14			-68	-60	
	Spurious free dynamic range	f _S = 480 kSPS, BW = 20 kHz, C _L = 100 pF,	$f_{OUT} = 1 \text{ kHz},$ $R_L = 10 \text{ k}\Omega,$ $T_A = 25^{\circ}\text{C}$, See Note 14		60	72	·	

NOTES: 13. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of 0x020 to 0x3DF or 0x3DF to 0x020. Limits are ensured by design and characterization, but are not production tested.



^{14. 1} kHz sinewave generated by DAC, reference voltage = 1.024 V at 3 V and 2.048 V at 5 V.

timing requirement

digital inputs

		MIN	NOM	MAX	UNIT
t _{su(CS-WE)}	Setup time, CS low before negative WE edge	13			ns
t _{su(D)}	Setup time, data ready before positive WE edge	9			ns
th(D)	Hold time, data held after positive WE edge	0			ns
t _{su(WE-LD)}	Setup time, positive WE edge before LDAC low	0			ns
twh(WE)	Pulse width, WE high	10			ns
t _{w(LD)}	Pulse width, LDAC low	10			ns

PARAMETER MEASUREMENT INFORMATION

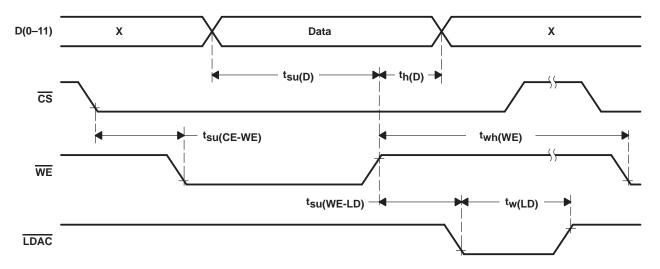
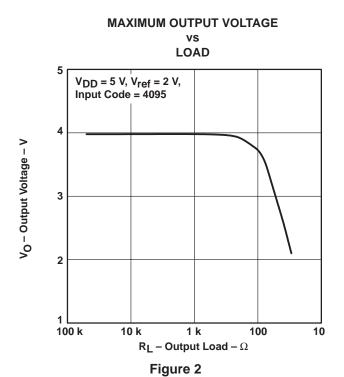
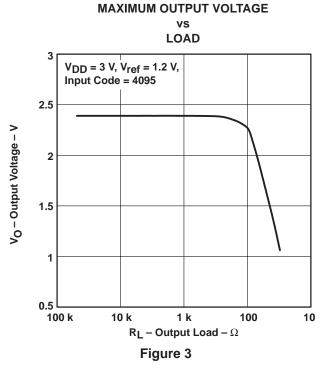


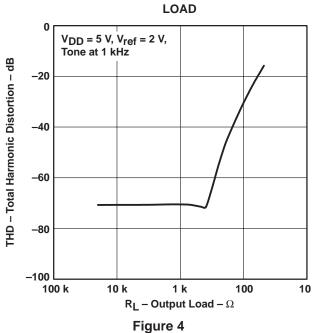
Figure 1. Timing Diagram

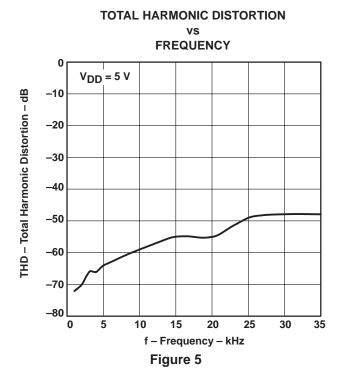
TYPICAL CHARACTERISTICS











TYPICAL CHARACTERISTICS

SIGNAL-TO-NOISE + DISTORTION **FREQUENCY** SNRD - Signal-To-Noise Ratio + Distortion - dB V_{DD} = 5 V

Figure 6

f - Frequency - kHz

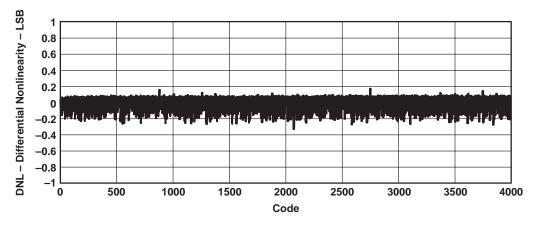


Figure 7. Differential Nonlinearity

TYPICAL CHARACTERISTICS

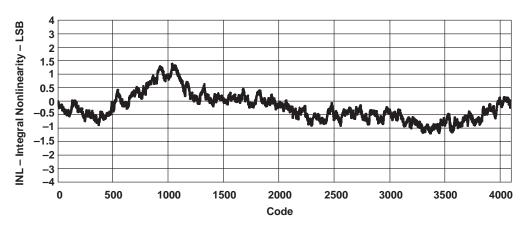


Figure 8. Integral Nonlinearity

POWER DOWN SUPPLY CURRENT

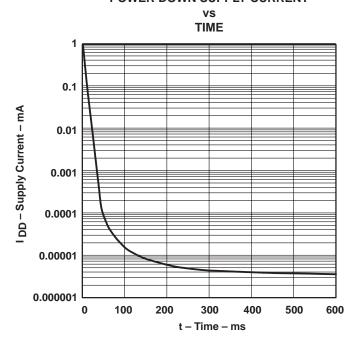


Figure 9.



APPLICATION INFORMATION

definitions of specifications and terminology

integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

zero-scale error (E_{7S})

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

gain error (E_G)

Gain error is the error in slope of the DAC transfer function.

signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

spurious free dynamic range (SFDR)

SFDR is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.

total harmonic distortion (THD)

THD is the ratio of the rms sum of the first six harmonic components to the rms value of the fundamental signal and is expressed in decibels.



APPLICATION INFORMATION

linearity, offset, and gain error using single end supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset the output voltage may not change with the first code depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 10.

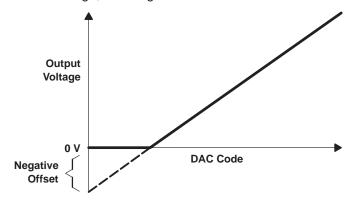


Figure 10. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero input code (all inputs 0) and full scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full scale code and the lowest code that produces a positive output voltage.

general function

The TLV5619 is a 12-bit, single supply DAC, based on a resistor string architecture. It consists of a parallel interface, a power down control logic, a resistor string, and a rail-to-rail output buffer. The output voltage (full scale determined by reference) is given by:

2 REF
$$\frac{\text{CODE}}{0 \times 1000}$$
 [V]

Where REF is the reference voltage and CODE is the digital input value, range 0x000 to 0xFFF. A power on reset initially puts the internal latches to a defined state (all bits zero).



APPLICATION INFORMATION

parallel interface

The device latches data on the positive edge of $\overline{\text{WE}}$. It must be enabled with $\overline{\text{CS}}$ low. $\overline{\text{LDAC}}$ low updates the DAC with the value in the holding latch. $\overline{\text{LDAC}}$ is an asynchronous input and can be held low, if a separate update is not necessary. However, to control the DAC using the load feature, $\overline{\text{LDAC}}$ can be driven low after the positive $\overline{\text{WE}}$ edge.

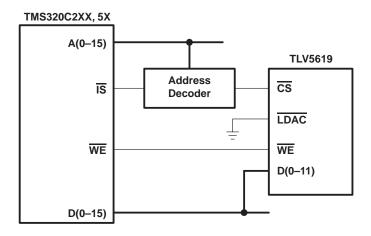


Figure 11. Proposed Interface Between TLV5619 and TMS320C2XX, 5X DSPs

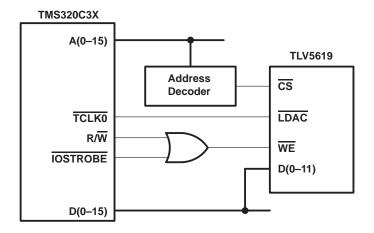


Figure 12. Proposed Interface Between TLV5619 and TMS320C3X DSPs

APPLICATION INFORMATION

TLV5619 interfaced to TMS320C203 DSP

hardware interface

Figure 13 shows an example of the connection between the TLV5619 and the TMS320C203 DSP. The only other device that is needed in addition to the DSP and the DAC is the 74AC138 address decoding circuit . Using this configuration, the DAC address is 0x0084 within the I/O memory space of the TMS320C203.

 $\overline{\text{LDAC}}$ is held low so that the output voltage is updated with the rising $\overline{\text{WE}}$ edge. The power down mode is deactivated permanently by pulling $\overline{\text{PD}}$ to V_{DD} .

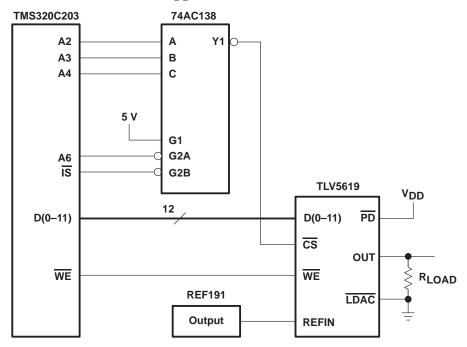


Figure 13. TLV5619 to TMS320C203 DSP Interface Connection

software

No setup procedure is needed to access the TLV5619. The output voltage can be set using one command:

out data_addr, DAC_addr

Where $data_addr$ points to the address location (in this example 0x0060) holding the new output voltage data and DAC_addr is the I/O space address of the TLV5619 (in this example 0x0084).

The following code shows, how to use the timer of the TMS320C203 as a time base to generate a voltage ramp with the TLV5619. A timer interrupt is generated every 205 μ s. The corresponding interrupt service routine increments the output code (stored at 0x0060) for the DAC and writes the new code to the TLV5619. Only the 12 LSBs of the data in 0x0060 are used by the DAC, so that the resulting period of the saw waveform is:

 $\tau = 4096 \times 205 \text{ E-6 s} = 0.84 \text{ s}$



APPLICATION INFORMATION

software listing

```
; File: ramp.asm
; Description: This program generates a ramp.
;----- I/O and memory mapped regs -----
       .include "regs.asm"
       .equ 0084h
TLV5619
;----- vectors -----
        .ps
             0h
        b
             start
        b
             INT1
        b
             INT23
        h
             TIM_ISR
* Main Program
****************
        .ps 1000h
        .entry
start:
        ldp
             #0
                  ; set data page to 0
; disable interrupts
             INTM ; disable maskable interrupts
        setc
             #Offffh, IFR
        splk
        splk
             #0004h,
                     IMR
; set up the timer
             #0000h,
                      60h
        splk
        splk
             #0042h,
             61h, PRD
60h, TIM
        out
        out
             #0c2fh, 62h, TCR
        splk
                      62h
        out
; enable interrupts
        clrc INTM ; enable maskable interrupts
; loop forever!
next
       idle
                  ; wait for interrupt
       b
               next
; all else fails stop here
                done ; hang there
done
******************
* Interrupt Service Routines
*******************
TNT1:
                  ; do nothing and return
      ret
INT23: ret
                  ; do nothing and return
TIM_ISR:
     ; useful code
        add
                #1h ; increment accumulator
        sacl
                  60h, TLV5619 ; write to DAC
        Out
        clrc
                intm; re-enable interrupts
                   ; return from interrupt
        ret
        .end
```

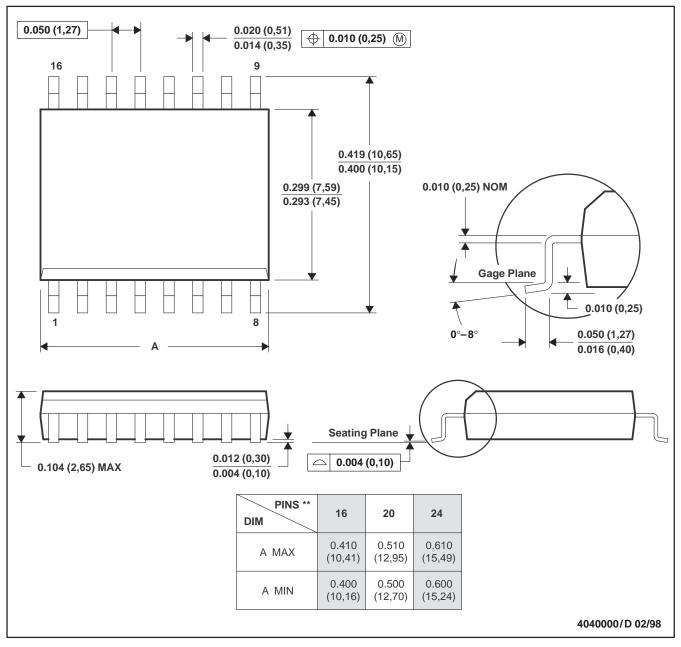


MECHANICAL DATA

DW (R-PDSO-G**)

16 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

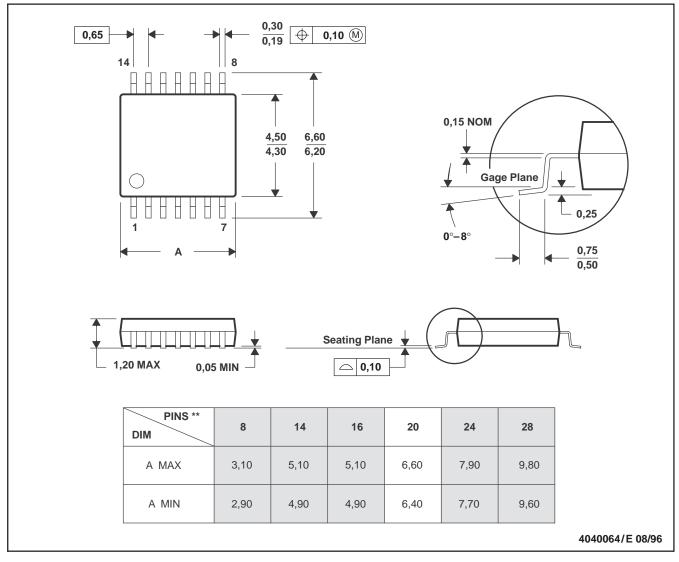


MECHANICAL DATA

PW (R-PDSO-G**)

14 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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